

In the Claims:

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1. (Currently Amended) A method of manufacturing a structural frame for dissipating heat from an electronic device, comprising:

providing a base polymer matrix;

mixing a thermally conductive filler material into said base polymer matrix to form molding material having a uniform distribution said filler material throughout said entire molding material;

net-shape injection molding said molding material into a structural frame for supporting electronic components;

providing an electronic circuit board, said electronic circuit board having a heat generating electronic component disposed thereon; and

mounting said electronic circuit board to in direct physical contact with said structural frame with said electronic component being in ~~physical contact with said structural frame, said electronic component thereby residing in~~ thermal communication with said structural frame via said electronic circuit board;

dissipating heat from said heat generating electronic component through said structural frame.

2. (Original) The method of manufacturing a structural frame of Claim 1, wherein said base polymer matrix is liquid crystal polymer.

3. (Original) The method of manufacturing a structural frame of Claim 1, wherein said thermally conductive filler material is selected from the group consisting of carbon fiber, metallic flakes, boron nitride and mixtures thereof.

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